

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HENKEL AG & CO. KGAA	01/05/2023
RECEIVING PARTY DATA	
Name:	HARIMA CHEMICALS GROUP, INC.
Street Address:	NIHONBASHI SAKURADORI BLDG. 5TH FLOOR
Internal Address:	3-8-4 NIHONBASHI, CHUO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	103-0027
PROPERTY NUMBERS Total: 8	
Property Type	Number
Patent Number:	8486498
Patent Number:	9427829
Patent Number:	9511453
Patent Number:	9682447
Patent Number:	10189121
Patent Number:	10376994
Application Number:	17675103
Patent Number:	11285569
CORRESPONDENCE DATA	
Fax Number:	(703)836-2021
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	703-836-6620
Email:	stacey.pflieger@bipc.com
Correspondent Name:	BUCHANAN INGERSOLL & ROONEY
Address Line 1:	1737 KING STREET
Address Line 4:	ALEXANDRIA, VIRGINIA 22314
ATTORNEY DOCKET NUMBER:	0077527-000059
NAME OF SUBMITTER:	STACEY PFLIEGER

SIGNATURE:	/StaceyPflieger/
DATE SIGNED:	01/24/2023
Total Attachments: 2 source=059assign#page1.tif source=059assign#page2.tif	

ASSIGNMENT

THIS ASSIGNMENT, by HENKEL AG & CO. KGAA, a corporation duly organized under and pursuant to the laws of GERMANY and having a principal place of business at Henkelstrasse 67, Duesseldorf 40589, Germany (hereinafter referred to as "the Assignor"), witnesseth:

WHEREAS, the Assignor has the entire right, title and interest in and to certain new and useful inventions set forth in the U.S. Patents listed in attached Appendix I, and an unspecified amount of right, title and interest in and to certain new and useful inventions set forth in the U.S. Patents and U.S. Patent Application listed in attached Appendix II;

WHEREAS, Harima Chemicals Group, Inc., a corporation duly organized under and pursuant to the laws of JAPAN and having a principal place of business at Nihonbashi Sakuradori Bldg., 5th floor, 3-8-4 Nihonbashi, Chuo-ku, Tokyo 103-0027, JAPAN (hereinafter referred to as "the Assignee"), is desirous of acquiring, and does hereby acquire, the entire right, title, and interest in and to said U.S. Patents of the United States listed in attached Appendix I, and the unspecified amount of right, title and interest in and to said U.S. Patent Application and U.S. Patents of the United States listed in attached Appendix II.

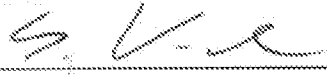
NOW, THEREFORE, for good and sufficient consideration, the receipt of which is hereby acknowledged, the Assignor hereby confirms any prior assignment to Assignee, and to the extent that Assignor has not already done so, agrees to assign, and hereby does sell, assign, transfer, and set over, unto the Assignee, its successors, legal representatives, and assigns the entire right, title, and interest in and to the U.S. Patents of the United States listed in attached Appendix I, and the unspecified amount of right, title and interest in and to the U.S. Patent Application and U.S. Patents of the United States listed in attached Appendix II, any U.S. Patent(s) that may be granted therefor and thereon, and reissues, reexamination, and extensions of said U.S. patents, and all rights under the International Convention for the Protection of Industrial Property, the same to be held and enjoyed by the Assignee, for its own use and behoof and the use and behoof of its successors, legal representatives, and assigns, to the full end of the term of said U.S. Patent Application and U.S. Patents listed in the attached Appendices as fully and entirely as the same would have been held and enjoyed by the Assignor had this sale and assignment not been made;

AND for the same consideration, the Assignor hereby covenants and agrees to and with the Assignee, its successors, legal representatives, and assigns, that, at the time of execution of these presents, the Assignor is the sole and lawful owner of the entire right, title, and interest in and to the inventions set forth in said U.S. Patents of the United States listed in attached Appendix I, and the unspecified amount of right, title and interest in and to the inventions set forth in said U.S. Patent Application and U.S. Patents of the United States listed in attached Appendix II, and that the same is unencumbered, and that the Assignor has good and full right and lawful authority to sell and convey the same in the manner herein set forth;

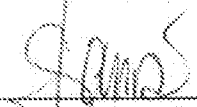
AND for the same consideration, the Assignor hereby covenants and agrees to and with the Assignee, its successors, legal representatives, and assigns that the Assignor will, whenever counsel of the Assignee, or the counsel of its successors, legal representatives, and assigns, shall advise that any proceeding in connection with said U.S. Patent Application and U.S. Patents listed in the attached Appendices, or any reissue, reexamination, or extension to be obtained thereon, is lawful and desirable, sign all papers and documents, take all lawful oaths, and do all acts necessary or required to be done for the procurement, maintenance, enforcement, and defense of said U.S. Patent Application and U.S. Patents listed in the attached Appendices for said inventions, without charge to the Assignee, its successors, legal representatives, and assigns, but at the cost and expense of the Assignee, its successors, legal representatives, and assigns.

HENKEL AG & CO. KGAA

DATE: January 05, 2023

Signature: 
Name/Title: Dr. Stefan Kucken, Corporate Director Legal

DATE: January 05, 2023

Signature: 
Name/Title: Dr. Markus Semrau, Corporate Director Legal

APPENDIX I

Application No.	Filing Date	Title	Patent No.	Issue Date	Recorded Reel / Frame
13/113,716	May 23, 2011	THERMALLY DECOMPOSABLE POLYMER COATED METAL POWDERS	8,486,498 B2	July 16, 2013	059357/0267
14/199,179	March 6, 2014	DI- OR POLY-FUNCTIONAL ELECTRON DEFICIENT OLEFINS COATED METAL POWDERS FOR SOLDER PASTE	9,427,829 B2	August 30, 2016	059357/0267
13/530,751	June 22, 2012	SOLDER PASTE COMPOSITION, A SOLDER PASTE AND A SOLDERING FLUX	9,511,453 B2	December 6, 2016	059357/0267
12/860,497	August 20, 2010	ORGANIC ACID- OR LATENT ORGANIC ACID-FUNCTIONALIZED POLYMER-COATED METAL POWDERS FOR SOLDER PASTES	9,682,447 B2	June 20, 2017	059357/0267
15/599,024	May 18, 2017	ORGANIC ACID-OR LATENT ORGANIC ACID-FUNCTIONALIZED POLYMER-COATED METAL POWDERS FOR SOLDER PASTES	10,189,121 B2	January 29, 2019	059357/0267

APPENDIX II

Application No.	Filing Date	Title	Patent No.	Issue Date	Recorded Reel / Frame
10/554,274	September 13, 2006	SOLDERING MATERIAL BASED ON SN AG AND CU	10,376,994 B2	August 13, 2019	025326/0562
16/530,053	August 2, 2019	SOLDERING MATERIAL BASED ON SN AG AND CU	11,285,569 B2	March 29, 2022	025326/0562
17/675,103	February 18, 2022	SOLDERING MATERIAL BASED ON SN AG AND CU			025326/0562

PATENT